

Multilayer Printed-wiring Board-Asia Pacific Market Status and Trend Report 2013-2023

<https://marketpublishers.com/r/MECFF193B8D8EN.html>

Date: May 2018

Pages: 148

Price: US\$ 3,480.00 (Single User License)

ID: MECFF193B8D8EN

Abstracts

Report Summary

Multilayer Printed-wiring Board-Asia Pacific Market Status and Trend Report 2013-2023 offers a comprehensive analysis on Multilayer Printed-wiring Board industry, standing on the readers' perspective, delivering detailed market data and penetrating insights. No matter the client is industry insider, potential entrant or investor, the report will provide useful data and information. Key questions answered by this report include:

Whole Asia Pacific and Regional Market Size of Multilayer Printed-wiring Board 2013-2017, and development forecast 2018-2023

Main market players of Multilayer Printed-wiring Board in Asia Pacific, with company and product introduction, position in the Multilayer Printed-wiring Board market
Market status and development trend of Multilayer Printed-wiring Board by types and applications

Cost and profit status of Multilayer Printed-wiring Board, and marketing status

Market growth drivers and challenges

The report segments the Asia Pacific Multilayer Printed-wiring Board market as:

Asia Pacific Multilayer Printed-wiring Board Market: Regional Segment Analysis (Regional Consumption Volume, Consumption Volume, Revenue and Growth Rate 2013-2023):

China

Japan

Korea

India

Southeast Asia

Australia

Asia Pacific Multilayer Printed-wiring Board Market: Product Type Segment Analysis
(Consumption Volume, Average Price, Revenue, Market Share and Trend 2013-2023):

Layer 4-6

Layer 8-10

Layer 10+

Asia Pacific Multilayer Printed-wiring Board Market: Application Segment Analysis
(Consumption Volume and Market Share 2013-2023; Downstream Customers and
Market Analysis)

Consumer Electronics

Communications

Computer Related Industry

Automotive Industry

Others

Asia Pacific Multilayer Printed-wiring Board Market: Players Segment Analysis
(Company and Product introduction, Multilayer Printed-wiring Board Sales Volume,
Revenue, Price and Gross Margin):

Nippon Mektron

Zhen Ding Technology

Unimicron

ELNA

Young Poong Group

Samsung Electro-Mechanics

Ibiden

Tripod

TTM Technologies

Sumitomo Electric SEI

Daeduck Group

Nanya PCB

Compeq

HannStar Board

LG Innotek

AT&S

Meiko

Chin-Poon

Shennan
WUS

In a word, the report provides detailed statistics and analysis on the state of the industry; and is a valuable source of guidance and direction for companies and individuals interested in the market.

Contents

CHAPTER 1 OVERVIEW OF MULTILAYER PRINTED-WIRING BOARD

- 1.1 Definition of Multilayer Printed-wiring Board in This Report
- 1.2 Commercial Types of Multilayer Printed-wiring Board
 - 1.2.1 Layer 4-6
 - 1.2.2 Layer 8-10
 - 1.2.3 Layer 10+
- 1.3 Downstream Application of Multilayer Printed-wiring Board
 - 1.3.1 Consumer Electronics
 - 1.3.2 Communications
 - 1.3.3 Computer Related Industry
 - 1.3.4 Automotive Industry
 - 1.3.5 Others
- 1.4 Development History of Multilayer Printed-wiring Board
- 1.5 Market Status and Trend of Multilayer Printed-wiring Board 2013-2023
 - 1.5.1 China Multilayer Printed-wiring Board Market Status and Trend 2013-2023
 - 1.5.2 Regional Multilayer Printed-wiring Board Market Status and Trend 2013-2023

CHAPTER 2 CHINA MARKET STATUS AND FORECAST BY REGIONS

- 2.1 Market Status of Multilayer Printed-wiring Board in China 2013-2017
- 2.2 Consumption Market of Multilayer Printed-wiring Board in China by Regions
 - 2.2.1 Consumption Volume of Multilayer Printed-wiring Board in China by Regions
 - 2.2.2 Revenue of Multilayer Printed-wiring Board in China by Regions
- 2.3 Market Analysis of Multilayer Printed-wiring Board in China by Regions
 - 2.3.1 Market Analysis of Multilayer Printed-wiring Board in North China 2013-2017
 - 2.3.2 Market Analysis of Multilayer Printed-wiring Board in Northeast China 2013-2017
 - 2.3.3 Market Analysis of Multilayer Printed-wiring Board in East China 2013-2017
 - 2.3.4 Market Analysis of Multilayer Printed-wiring Board in Central & South China 2013-2017
 - 2.3.5 Market Analysis of Multilayer Printed-wiring Board in Southwest China 2013-2017
 - 2.3.6 Market Analysis of Multilayer Printed-wiring Board in Northwest China 2013-2017
- 2.4 Market Development Forecast of Multilayer Printed-wiring Board in China 2018-2023
 - 2.4.1 Market Development Forecast of Multilayer Printed-wiring Board in China 2018-2023

2.4.2 Market Development Forecast of Multilayer Printed-wiring Board by Regions 2018-2023

CHAPTER 3 CHINA MARKET STATUS AND FORECAST BY TYPES

3.1 Whole China Market Status by Types

3.1.1 Consumption Volume of Multilayer Printed-wiring Board in China by Types

3.1.2 Revenue of Multilayer Printed-wiring Board in China by Types

3.2 China Market Status by Types in Major Countries

3.2.1 Market Status by Types in North China

3.2.2 Market Status by Types in Northeast China

3.2.3 Market Status by Types in East China

3.2.4 Market Status by Types in Central & South China

3.2.5 Market Status by Types in Southwest China

3.2.6 Market Status by Types in Northwest China

3.3 Market Forecast of Multilayer Printed-wiring Board in China by Types

CHAPTER 4 CHINA MARKET STATUS AND FORECAST BY DOWNSTREAM INDUSTRY

4.1 Demand Volume of Multilayer Printed-wiring Board in China by Downstream Industry

4.2 Demand Volume of Multilayer Printed-wiring Board by Downstream Industry in Major Countries

4.2.1 Demand Volume of Multilayer Printed-wiring Board by Downstream Industry in North China

4.2.2 Demand Volume of Multilayer Printed-wiring Board by Downstream Industry in Northeast China

4.2.3 Demand Volume of Multilayer Printed-wiring Board by Downstream Industry in East China

4.2.4 Demand Volume of Multilayer Printed-wiring Board by Downstream Industry in Central & South China

4.2.5 Demand Volume of Multilayer Printed-wiring Board by Downstream Industry in Southwest China

4.2.6 Demand Volume of Multilayer Printed-wiring Board by Downstream Industry in Northwest China

4.3 Market Forecast of Multilayer Printed-wiring Board in China by Downstream Industry

CHAPTER 5 MARKET DRIVING FACTOR ANALYSIS OF MULTILAYER PRINTED-

WIRING BOARD

5.1 China Economy Situation and Trend Overview

5.2 Multilayer Printed-wiring Board Downstream Industry Situation and Trend Overview

CHAPTER 6 MULTILAYER PRINTED-WIRING BOARD MARKET COMPETITION STATUS BY MAJOR PLAYERS IN CHINA

6.1 Sales Volume of Multilayer Printed-wiring Board in China by Major Players

6.2 Revenue of Multilayer Printed-wiring Board in China by Major Players

6.3 Basic Information of Multilayer Printed-wiring Board by Major Players

6.3.1 Headquarters Location and Established Time of Multilayer Printed-wiring Board Major Players

6.3.2 Employees and Revenue Level of Multilayer Printed-wiring Board Major Players

6.4 Market Competition News and Trend

6.4.1 Merger, Consolidation or Acquisition News

6.4.2 Investment or Disinvestment News

6.4.3 New Product Development and Launch

CHAPTER 7 MULTILAYER PRINTED-WIRING BOARD MAJOR MANUFACTURERS INTRODUCTION AND MARKET DATA

7.1 Nippon Mektron

7.1.1 Company profile

7.1.2 Representative Multilayer Printed-wiring Board Product

7.1.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Nippon Mektron

7.2 Zhen Ding Technology

7.2.1 Company profile

7.2.2 Representative Multilayer Printed-wiring Board Product

7.2.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Zhen Ding Technology

7.3 Unimicron

7.3.1 Company profile

7.3.2 Representative Multilayer Printed-wiring Board Product

7.3.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Unimicron

7.4 ELNA

7.4.1 Company profile

- 7.4.2 Representative Multilayer Printed-wiring Board Product
- 7.4.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of ELNA
- 7.5 Young Poong Group
 - 7.5.1 Company profile
 - 7.5.2 Representative Multilayer Printed-wiring Board Product
 - 7.5.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Young Poong Group
- 7.6 Samsung Electro-Mechanics
 - 7.6.1 Company profile
 - 7.6.2 Representative Multilayer Printed-wiring Board Product
 - 7.6.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Samsung Electro-Mechanics
- 7.7 Ibiden
 - 7.7.1 Company profile
 - 7.7.2 Representative Multilayer Printed-wiring Board Product
 - 7.7.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Ibiden
- 7.8 Tripod
 - 7.8.1 Company profile
 - 7.8.2 Representative Multilayer Printed-wiring Board Product
 - 7.8.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Tripod
- 7.9 TTM Technologies
 - 7.9.1 Company profile
 - 7.9.2 Representative Multilayer Printed-wiring Board Product
 - 7.9.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of TTM Technologies
- 7.10 Sumitomo Electric SEI
 - 7.10.1 Company profile
 - 7.10.2 Representative Multilayer Printed-wiring Board Product
 - 7.10.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Sumitomo Electric SEI
- 7.11 Daeduck Group
 - 7.11.1 Company profile
 - 7.11.2 Representative Multilayer Printed-wiring Board Product
 - 7.11.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Daeduck Group
- 7.12 Nanya PCB

- 7.12.1 Company profile
- 7.12.2 Representative Multilayer Printed-wiring Board Product
- 7.12.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Nanya PCB
- 7.13 Compeq
 - 7.13.1 Company profile
 - 7.13.2 Representative Multilayer Printed-wiring Board Product
 - 7.13.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of Compeq
- 7.14 HannStar Board
 - 7.14.1 Company profile
 - 7.14.2 Representative Multilayer Printed-wiring Board Product
 - 7.14.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of HannStar Board
- 7.15 LG Innotek
 - 7.15.1 Company profile
 - 7.15.2 Representative Multilayer Printed-wiring Board Product
 - 7.15.3 Multilayer Printed-wiring Board Sales, Revenue, Price and Gross Margin of LG Innotek
- 7.16 AT&S
- 7.17 Meiko
- 7.18 Chin-Poon
- 7.19 Shennan
- 7.20 WUS

CHAPTER 8 UPSTREAM AND DOWNSTREAM MARKET ANALYSIS OF MULTILAYER PRINTED-WIRING BOARD

- 8.1 Industry Chain of Multilayer Printed-wiring Board
- 8.2 Upstream Market and Representative Companies Analysis
- 8.3 Downstream Market and Representative Companies Analysis

CHAPTER 9 COST AND GROSS MARGIN ANALYSIS OF MULTILAYER PRINTED-WIRING BOARD

- 9.1 Cost Structure Analysis of Multilayer Printed-wiring Board
- 9.2 Raw Materials Cost Analysis of Multilayer Printed-wiring Board
- 9.3 Labor Cost Analysis of Multilayer Printed-wiring Board
- 9.4 Manufacturing Expenses Analysis of Multilayer Printed-wiring Board

CHAPTER 10 MARKETING STATUS ANALYSIS OF MULTILAYER PRINTED-WIRING BOARD

- 10.1 Marketing Channel
 - 10.1.1 Direct Marketing
 - 10.1.2 Indirect Marketing
 - 10.1.3 Marketing Channel Development Trend
- 10.2 Market Positioning
 - 10.2.1 Pricing Strategy
 - 10.2.2 Brand Strategy
 - 10.2.3 Target Client
- 10.3 Distributors/Traders List

CHAPTER 11 REPORT CONCLUSION

CHAPTER 12 RESEARCH METHODOLOGY AND REFERENCE

- 12.1 Methodology/Research Approach
 - 12.1.1 Research Programs/Design
 - 12.1.2 Market Size Estimation
 - 12.1.3 Market Breakdown and Data Triangulation
- 12.2 Data Source
 - 12.2.1 Secondary Sources
 - 12.2.2 Primary Sources
- 12.3 Reference

I would like to order

Product name: Multilayer Printed-wiring Board-Asia Pacific Market Status and Trend Report 2013-2023

Product link: <https://marketpublishers.com/r/MECFF193B8D8EN.html>

Price: US\$ 3,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/MECFF193B8D8EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970